

Title (en)  
DEVICE FOR A TWIN-DISK LAPPING MACHINE

Publication  
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Application  
**EP 89902018 A 19890217**

Priority  
CH 127788 A 19880407

Abstract (en)  
[origin: WO8909679A1] A beam (11) is arranged generally vertically on the upper end of a radially-rotatable pillar support (3) in such a way that it can pivot around its generally central part. A tool spindle (15) is mounted axially, in a non-adjustable position, on the front end (13) of the beam in a spindle head (14) connected to the beam (11) and is driven by a first driving means (17). The upper tool disk (21) is mounted at the lower end of the tool spindle (15) on an articulated head (20). The pillar support (3), which is positioned and guided in the support guiding device (2), can be raised and lowered by means of a lifting spindle (4) driven by a second driving means (6) in order to bring the tool disk (21) into its working position. A first adjusting means (29) engaged on the rear end (28) of the beam is used to maintain the beam (11) in a generally horizontal position. A second adjusting means (30) which is also engaged on the rear end (28) of the beam is used to control the working pressure of the tool disk (21). The design of said invention provides an easy solution for suspending, positioning and driving the tool disk (21) because the tool spindle (15) can no longer be axially shifted. The working pressure of the tool disk (21) can be controlled with high precision. Lapping machines according to said invention are particularly suited for processing wafers, quartz and thin-walled ceramic plates.

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